Product End-of-Life Disassembly Instructions

Product Category: Calculators
Marketing Name / Model [List multiple models if applicable.]
HP 5830AF-96G Series Switch Chassis（JG374A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		4
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on Holder 1, and then remove Holder 1.
2. Unscrew all screws 2 and 5, and then remove panel 3 and the mounting angle 4.
3. Remove part 5 from the chassis.
4. Remove top cover 7, and then remove plastic panel 6 from the chassis.
5. Remove all of the inner cables.
6. Unscrew the screws on cover 9, and then remove cover 9 from the chassis.
7. Unscrew all screws of battery 10, and then remove battery 10 from the chassis.
8. Unscrew all s, and then remove panel 10 from base 8.
9. Unscrew all screws on fan 11, and then remove fan 11 from the chassis.
10. Unscrew all screws on part 12, and then remove part 12 from the chassis.
11. Unscrew all screws of PCB 13, and then remove PCB 13 from the chassis.
12. Unscrew all screws on fan rack 14, and then remove fan rack 14 from the chassis.
13. Unscrew all screws on support 15, and then remove support 15 from the chassis.
14. Unscrew all screws on PCB 16, and then remove PCB 16 from the chassis.
15. Remove all of the labels from the chassis.
16. Unscrew all screws 11-2, and then remove part 11-3 from part 11-1.
17. Unscrew all screws on cover 14-5, and then remove cover 14-5 from fan rack 14.
18. Unscrew the screw 14-2, and then remove fan 14-4 from fan rack 14-3.
19. Unscrew the screws on PCB 14-6, and then remove PCB 14-6 from fan rack 14.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

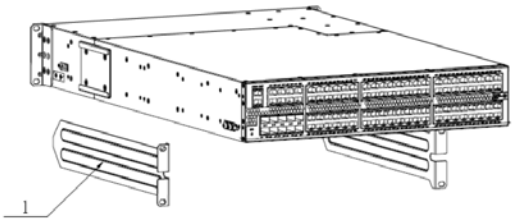

Figure 1 Remove holder 1

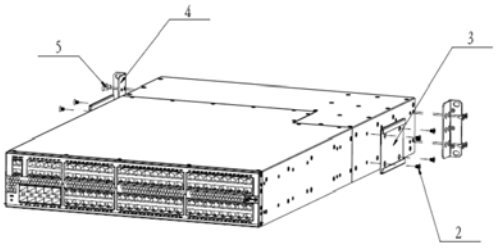

Figure 2 Treatments to the product(I)

PSG instructions for this template are available at EL-MF877-01

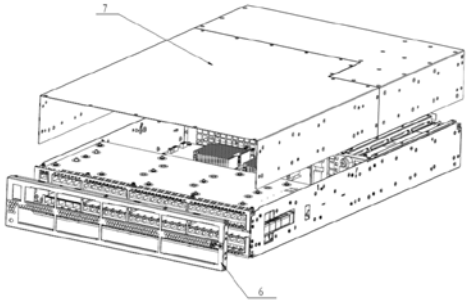

Figure 3 Remove plastic panel 6 and top cover 7

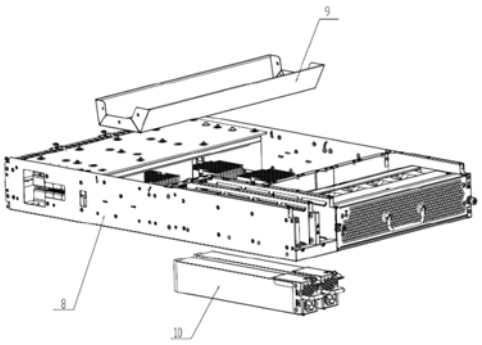

Figure 4 Remove cover 9 and battery 10

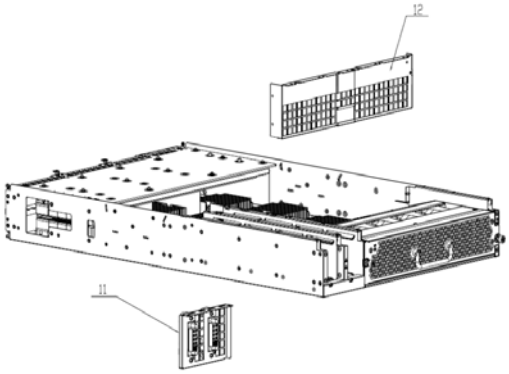

Figure 5 Remove part 11 and part 12

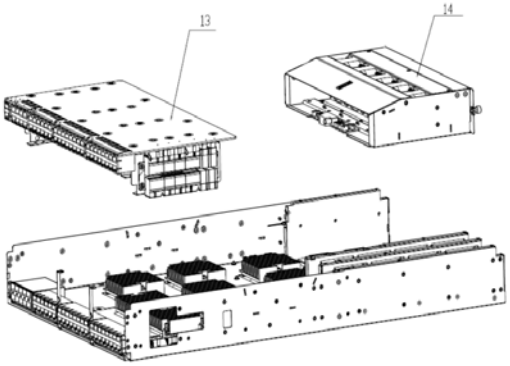

Figure 6 Remove PCB 13 and fan 14

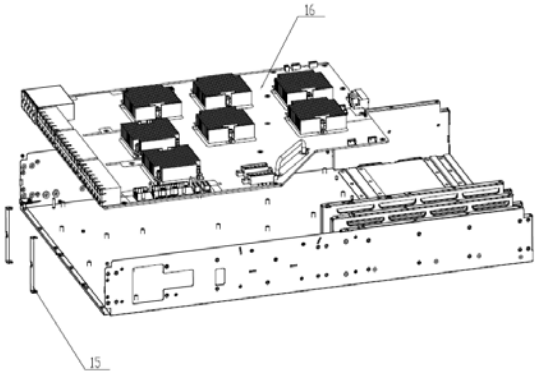

Figure 7 TRemove Support 15 and PCB 16

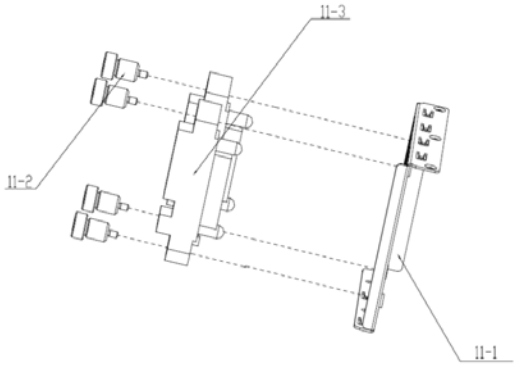

Figure 8 Treatments to part 11

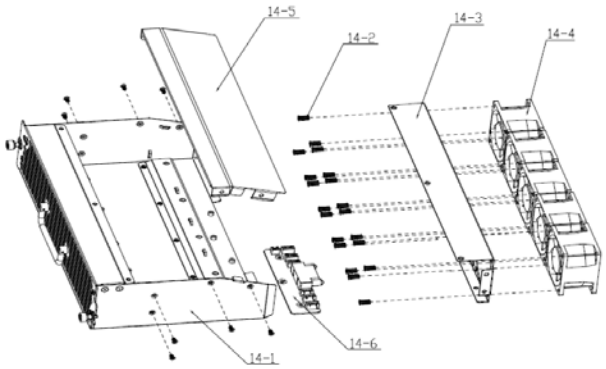

Figure 9 Treatments to fan rack 14

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	7,8	Fe	10450	59.27%		Fe recycling
	10		1160	6.58%		
	13	Complex PWB	1150	6.52%	The surface of PCB is greater than 10 square centimeters;	
14			1567	8.89%		
	14-1	Fe	1410	8.00%		Fe recycling
	14-4	PBT , Cu	110	0.62%	Containing brominated flame retardants	Pla recycling Cu recycling
	14-6	Complex PWB	40	0.23%	The surface of PCB is greater than 10 square centimeters;	
	16	Complex PWB	3310	18.74%	The surface of PCB is greater than 10 square centimeters;	